

ATTENTION
 OBSERVE PRECAUTIONS
 FOR HANDLING
 ELECTROSTATIC
 DISCHARGE
 SENSITIVE
 DEVICES

HL-304S33YD

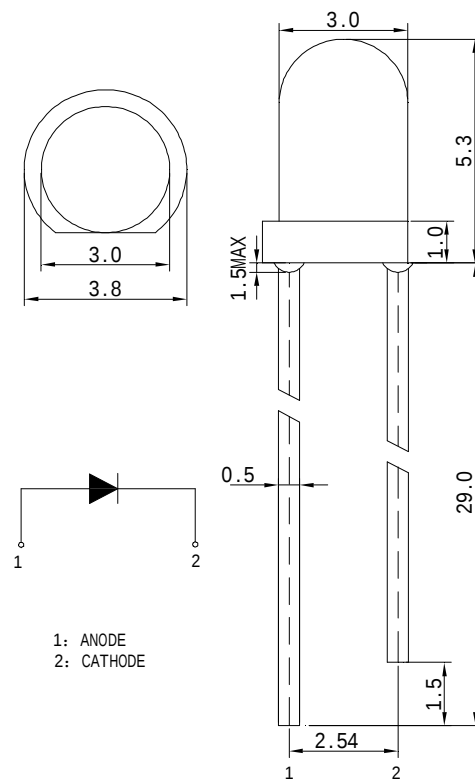

Features

- $\phi 3$ LAMP LED
- LOW POWER CONSUMPTION.
- CABINED VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE: 1000PCS / BAG.

Description

This devices are made with TS A1InGaP.

Package Dimensions



Tolerance Grade	Dimension Tolerance (UNIT:mm)			
	0.5~3	3~6	6~30	30~120
Medium(m)	± 0.1	± 0.2	± 0.3	± 0.5
Chip		Lens Color		
Material	Emitting Color	Color Diffused		
A1InGaP	Yellow			

■ Absolute Maximum Rating

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	I_F	20	mA
Peak Forward Current*	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	80	mW
Electrostatic discharge	E_{SD}	2000	V
Operation Temperature	T_{opr}	-30~+80	°C
Storage Temperature	T_{stg}	-30~+80	°C
Lead Soldering Temperature*	T_{sol}	Max. 260°C for 5sec Max.	

* I_{FP} Conditions: Pulse Width $\leq 10\text{msec}$

* T_{sol} Conditions: 3mm from the base of the epoxy bulb

■ Typical Optical/ Electrical Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	1.8	2.2	2.6	V
50% Power Angle	$2\theta_{1/2}$		--	40	--	deg
Luminous Intensity	I_v		210	270	--	mcd
Prpcp Wavelength	λ_D		585	--	595	nm
Recommend Forward Current	$I_F(\text{rec})$	--	--	--	20	mA
Reverse Current	I_R	$V_R=5\text{V}$	--	--	20	uA

Notes:

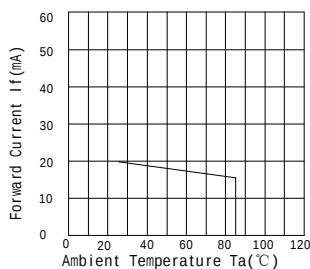
1. Absolute maximum ratings $T_a=25^\circ\text{C}$.
2. Tolerance of measurement of forward voltage $\pm 0.1\text{V}$.
3. Tolerance of measurement of peak Wavelength $\pm 2.0\text{nm}$.
4. Tolerance of measurement of luminous intensity $\pm 15\%$.
5. Tolerance of measurement of angle intensity $\pm 15\%$.

Reliability Performance Test Items And Result

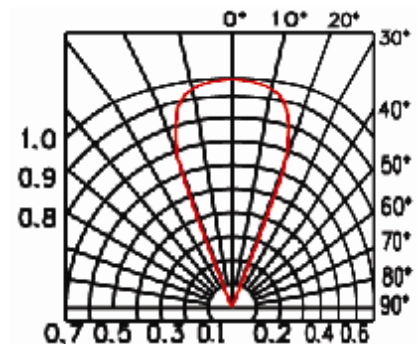
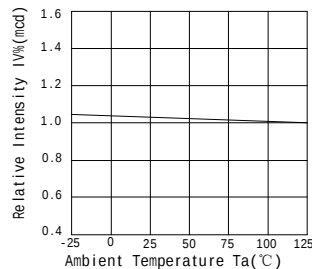
Test Classification	Test Item	Test Conditions	Test Duration	Sample Size	AC/RE
Life Test	Room Temperature DC Operating Life Test	$T_a=25^{\circ}\text{C}\pm 5^{\circ}\text{C}$, $I_F=20\text{mA}$	1000 hrs	22pcs	0/1
Environment Test	Thermal Shock Test	$100^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 5min $\uparrow \downarrow$ $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 5min.	100 cycles	22pcs	0/1
	Temperature Cycle Test	$100^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 30min $\uparrow \downarrow$ 5min $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 30min.	100 cycles	22 pcs	0/1
	High Temperature & High Humidity Test	$85^{\circ}\text{C}\pm 5^{\circ}\text{C}/85\%\text{ RH}$ $I_F=5\text{mA}$	1000 hrs	22pcs	0/1
	High Temperature Storage	$T_a=100^{\circ}\text{C}\pm 5^{\circ}\text{C}$	1000 hrs	22 pcs	0/1
	Low Temperature Storage	$T_a=-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$	1000 hrs	22 pcs	0/1
Mechanical Test	Resistance to Soldering Heat	Temp= 260°C max T=5sec max	1times	22 pcs	0/1
	Lead Integrity	Load 2.5N(0.25kgf) $0^{\circ} \sim 90^{\circ} \sim 0^{\circ}$	3times	22 pcs	0/1

The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced. It does not constitute the warranting of industrial property nor the granting of any license.

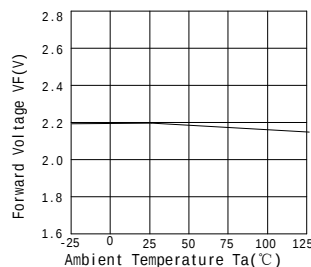
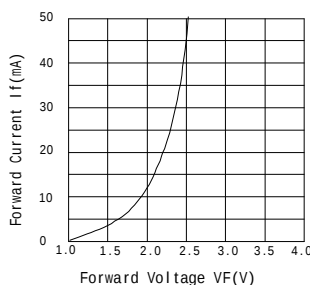
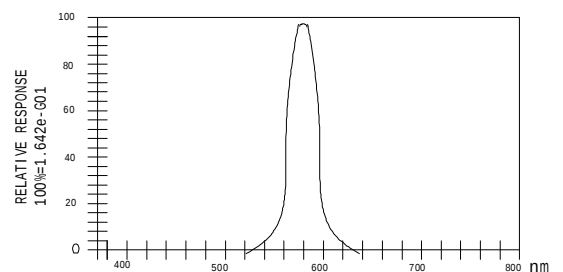
Forward Current vs. Ambient Temperature



Relative Intensity vs. Ambient Temperature



Forward Current vs. Forward Voltage


 Luminous Spectrum ($T_a=25^{\circ}\text{C}$) SPECTRAL RADIANCE




Soldering:

1. Manual Of Soldering

The temperature of the iron tip should not be higher than 260°C (500°F) and Soldering within 3 seconds per solder-land is to be observed.

2. DIP soldering (Wave Soldering):

Preheating: 120°C ~ 150°C , within 120~180 sec.

Operation heating: $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).

